### I.SCOPE:

This specification applies to the Pb Free high current type SMD inductors for MSI-121006-SERIES

#### PRODUCT INDENTIFICATION

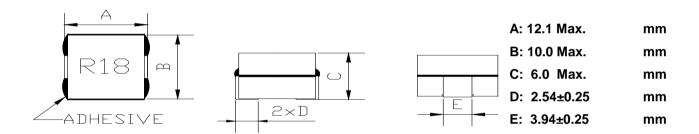
### MSI-121006- R18 M

- 1 2
- (3)

4

- 1) Product Code
- 2 Dimensions Code
- **3 Inductance Code**
- **4** Tolerance Code

# (1) SHAPES AND DIMENSIONS



# (2) ELECTRICAL SPECIFICATIONS SEE TABLE 1

**TEST INSTRUMENTS** 

L: HP 4284A PRECISION LCR METER (or equivalent)

RDC: CHROMA MODEL 16502 MILLIOHMMETER (or equivalent)

IDC1:WK3255B+3265B (or equivalent)

# (3) CHARACTERISTICS

(3)-1 Operate temperature range ......  $-40^{\circ}$ C  $\sim +125^{\circ}$ C (Including self temp. rise)

(3)-2 Storage temperature range .....  $-40^{\circ}$ C  $\sim +125^{\circ}$ C



### **TABLE**

MAGLAYERS	Inductance	Percent	Test	Resistance	Rated DC Current		Maukina
PT/NO.	L(µH)	Tolerance	Frequency	RDC(mΩ)	IDC1(A)	IDC2(A)	Marking
MSI-121006-R18□	0.18	L,M	100kHz/0.1V	0.48 ±6.5%	55	36	R18
MSI-121006-R23□	0.23	L,M	100kHz/0.1V	0.48 ±6.5%	47	36	R23
MSI-121006-R36□	0.36	L,M	100kHz/0.1V	0.48 ±6.5%	30	36	R36

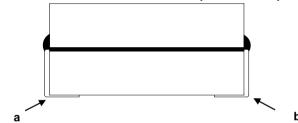
★ □ specify the inductance tolerance,L(±15%),M(±20%)

※ IDC1: Based on inductance change (△L/Lo: drop 20% Typ.)@ ambient temp. 25°C

IDC2 : Based on temperature rise ( $\triangle T$ : 40°C TYP.) Rated DC Current : The less value which is IDC1 or IDC2 .

### **RDC TEST POINT**

The nominal DCR is measured from point "a" to point "b" .



# (4) RELIABILITY TEST METHOD

SPECIFICATION	TEST DETAILS			
∆L/Lo≦±5%	The sample shall be soldered onto the printed circuit board			
	in figure 1 and a load applied unitil the figure in the arrow			
There shall be	direction is made approximately 3mm.(keep time 30 seconds)			
no mechanical	PCB dimension shall the page 7/9			
damage or elec-	F(Pressurization)			
trical damege.				
	R5 45±2 45±2 10 20 R340			
	PRESSURE ROD figure-1			
∆L/Lo≦±5%	The sample shall be soldered onto the printed circuit board			
	and when a vibration having an amplitude of 1.52mm			
There shall be	and a frequency of from 10 to 55Hz/1 minute repeated should			
no mechanical	be applied to the 3 directions (X,Y,Z) for 2 hours each.			
damage.	(A total of 6 hours)			
New solder	Flux (rosin, isopropyl alcohol{JIS-K-1522}) shall be coated			
More than 90%	over the whole of the sample before hard, the sample shall			
	then be preheated for about 2 minutes in a temperature of			
	130∼150℃ and after it has been immersed to a depth 0.5mm			
	below for 3±0.2 seconds fully in molten solder M705 with			
	a temperature of 245±5℃.			
	More than 90% of the electrode sections shall be couered			
	with new solder smoothly when the sample is taken out of			
	the solder bath.			
	△L/Lo≦±5%  There shall be no mechanical damage or electrical damege.  △L/Lo≦±5%  There shall be no mechanical damage.  New solder			



# **MECHANICAL**

TEST ITEM	SPECIFICATION					
Resistance to	There shall be	Temperature profile of reflow soldering				
Soldering heat	no damage or					
(reflow soldering)	problems.	The specimen shall be passed through the reflow oven with the condition shown in the above profile for 1 time.  The specimen shall be stored at standard atmospheric conditions for 1 hour, after which the measurement shall be made.				

## **ELECTRICAL**

TEST ITEM	SPECIFICATION	TEST DETAILS		
Temperature	∆L/L20°C ≦±10%	The test shall be performed after the sample has stabilized in		
characteristics	0~2000 ppm/℃	an ambient temperature of -20 to +85℃,and the value		
		calculated based on the value applicable in a normal		
		temperature and narmal humidity shall be △L/L20°C ≦±10%.		

## **ENVIROMENT CHARACTERISTICS**

TEST ITEM				SPECIFICATION				
High temperature	∆L/Lo≦±5%	The san	The sample shall be left for 96±4 hours in an atmospere with					
storage		a tempe	a temperature of 125 $^{\circ}\!$					
	There shall be	Upon co	Upon completion of the measurement shall be made after the					
	no mechanical	sample	sample has been left in a normal temperature and normal					
	damage.	humidit	humidity for 1 hour.					
Low temperature	∆L/Lo≦±5%	The san	The sample shall be left for 96±4 hours in an atmosphere with					
storage		a tempe	a temperature of -25±3℃.					
	There shall be	Upon co	Upon completion of the test, the measurement shall be made					
	no mechanical	after the	after the sample has been left in a normal temperature and					
	damage.	normal humidity for 1 hour.						
Change of	∆L/Lo≦±5%	The san	The sample shall be subject to 5 continuos cycles, such as shown					
temperature		in the ta	in the table 2 below and then it shall be subjected to standard					
	There shall be	stmosp	stmospheric conditions for 1 hour, after which measurement					
	no other dama-	shall be	shall be made.					
	ge of problems							
				table 2				
				Temperature	Duration			
			1	-25±3℃	30 min.			
				(Themostat No.1)				
			2	Standard	No.1→No.2			
				atmospheric	140.1 > 140.2			
			3	<b>85±2</b> ℃	30 min.			
				(Themostat No.2)				
			4	Standard	No.2→No.1			
				atmospheric				
Moisture storage		The san	The sample shall be left for 96±4 hours in a temperature of					
			-	humidity(RH) of 90~95	-			
	There shall be		Upon completion of the test, the measurement shall be made					
	no mechanical	after the sample has been left in a normal temperature and						
	damage.	normal humidity more than 1 hour.						
Test conditions :				-				
	sample shall be reflo	w soldere	d onto	the printed circuit boa	rd in every test.			

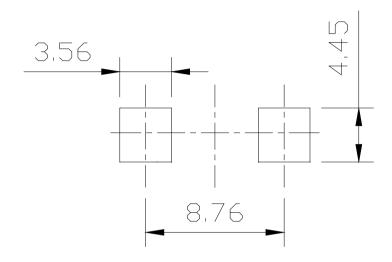


# (5) LAND DIMENSION (Ref.)

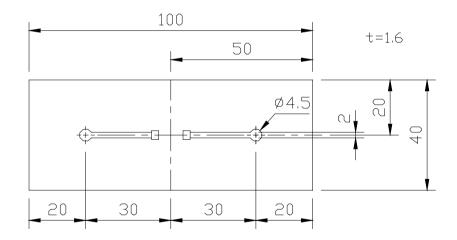
PCB: GLASS EPOXY t=1.6mm

## (5)-1 LAND PATTERN DIMENSIONS(mm)

(STANDARD PATTERN)

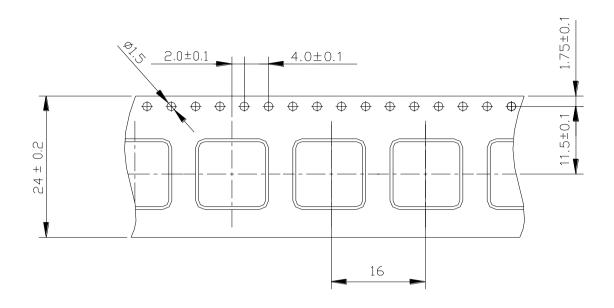


# (5)-2 SUBSTRATE BENDING TEST BENDING TEST BOARD

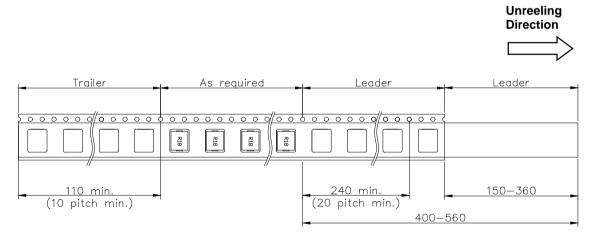


# (6) PACKAGING

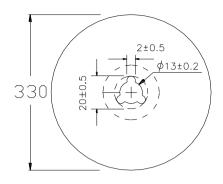
## (6)-1 CARRIER TAPE DIMENSIONS (mm)

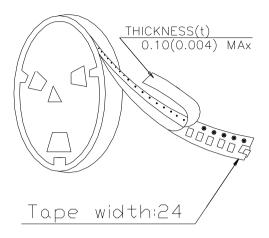


## (6)-2 TAPING DIMENSIONS (mm)



# (6)-3 REEL DIMENSIONS (mm)





# (6)-4 QUANTITY

500pcs/Reel

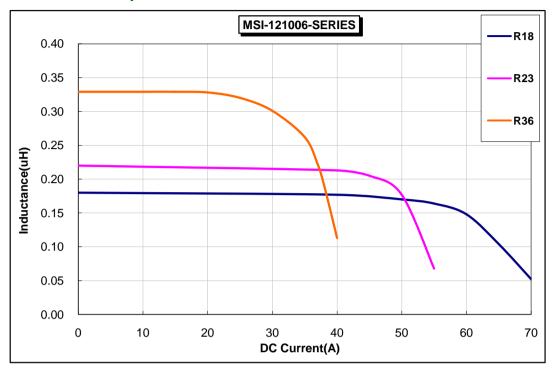
The products are packaged so that no damage will be sustained.



### TYPICAL ELECTRICAL CHARACTERISTICS

# INDUCTANCE vs. DC CURRENT@100kHz/0.1V

**Ambient Temperature : 25℃** 



# **Temperature Rise vs. DC Current**

